

S/N 09/483,881

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Examiner: Ha Nguyen

Serial No.: 09/483,881

Group Art Unit: 2812

Filed: January 18, 2000

Docket No.: 303.672US1

Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant has reviewed the Office Action mailed on June 30, 2003.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a 1-month extension of the period for responding to the Office action, thereby moving the deadline for response from September 30, 2003 to October 30, 2003.

REMARKS

In response to the Office Action mailed on June 30, 2003, no changes are made to the claims. Consequently, claims 3, 5, 7-42 and 65 remain pending in this application.

§103 Rejection of the Claims

Claims 3, 5, 7-12, and 65 were rejected under 35 USC § 103(a) as being unpatentable Tan et al. (U.S. Patent No. 6,372,622, "Tan") or Farnworth et al. (U.S. Patent No. 5,495,667, "Farnworth") in view of Bernier et al. ("Laser Processing of Palladium...", hereinafter "Bernier") or Dubin et al. ("Selective and Blanket Electroless Copper Deposition...", hereinafter "Dubin"). Applicant is assuming that the Examiner meant to identify U.S. Patent No. 5,495,667 as "Farnworth" and not "Earnworth", and Applicant also assumes that the Examiner meant to say "Dubin" and not "Diamand" when referring to the "Copper Electroless Deposition..." reference as there is no document attributed to "Diamand" on record.

Concerning claim 7:

Applicant respectfully traverses the rejection. The Office Action fails to establish a proper *prima facie* case of obviousness for the reasons stated below.

Combinations including Bernier teach away from the present invention:

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